



# 正基科技股份有限公司

## SPECIFICATION

**PRODUCT NAME :** AP6275P

**REVISION :** 0.5

**DATE :** Mar 06<sup>th</sup>, 2020

Customer APPROVED	
Company	
Representative Signature	

PREPARED	REVIEW		APPROVED	DCC ISSUE
	PM	QA		





# 正基科技股份有限公司



## AP6275P

Data Sheet

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# Revision

Revision	Date	Description	Revised By
0.1	2018/12/10	- Preliminary	Richard
0.2	2018/12/11	- Modify Dimension	Richard
0.3	2019/05/09	- Modify information	Benson
0.4	2019/11/27	- Modify footprint define - Modify Label - Add ESD Specification - Add External 37.4MHz X`tal characteristics	Jason
0.5	2020/03/06	-Modify RF Specification	Jason



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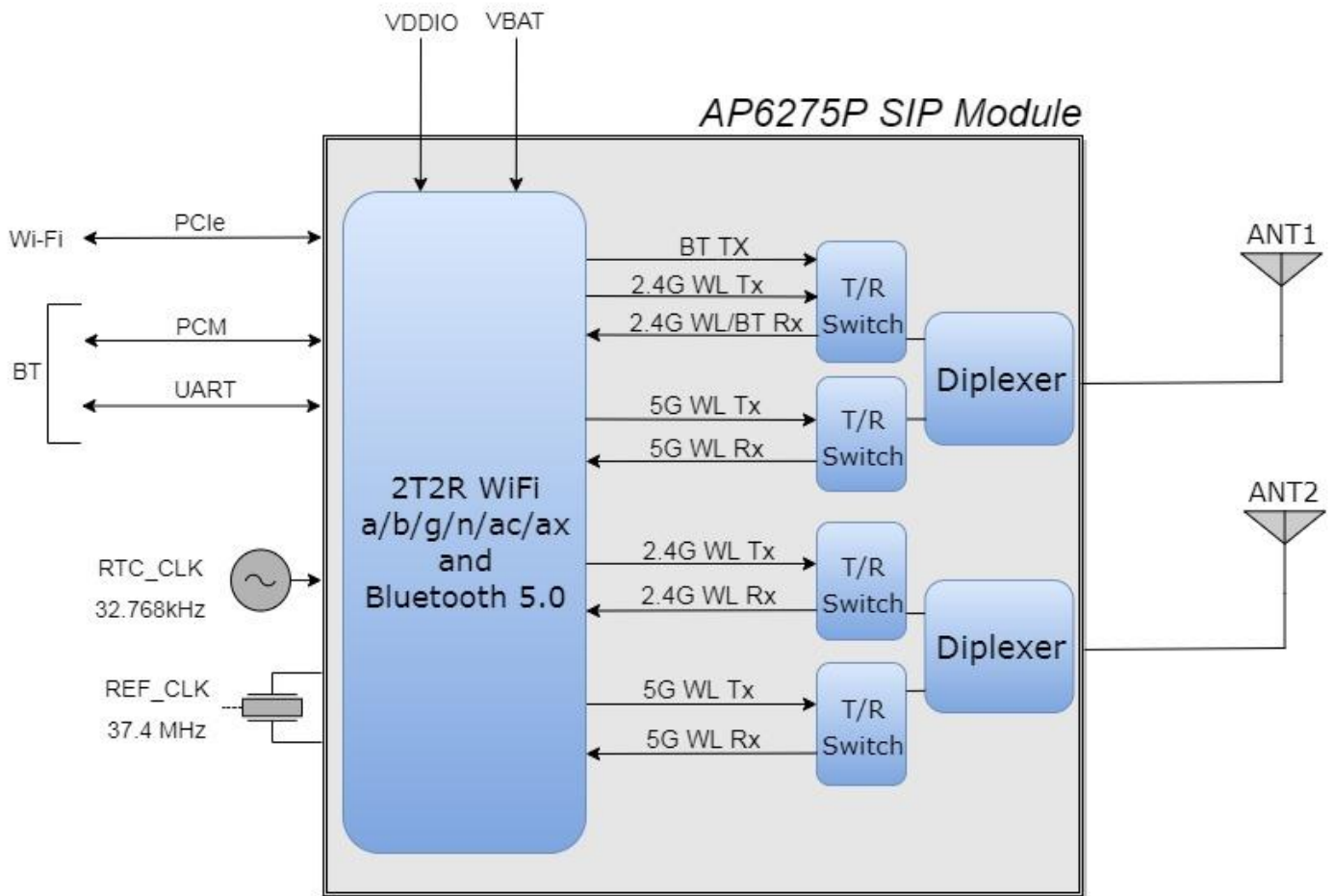


# 1. Introduction

## 1.1 Overview

The AMPAK Technology® AP6275P is a fully Wi-Fi and Bluetooth functionalities module with seamless roaming capabilities and advance security, also it could interact with different vendors' 802.11a/b/g/n/ac/ax 2x2 Access Points with MIMO standard and can accomplish up to speed of 1200Mbps with dual stream in 802.11ax to connect the wireless LAN. Furthermore AP6275P included PCIe interface for Wi-Fi, UART/ PCM interface for Bluetooth.

In addition, this compact module is a total solution for a combination of Wi-Fi + BT technologies. The module is specifically developed for tablet, OTT box and portable devices.



## 1.2 Product Features

- Lead Free design which is compliant with ROHS requirements.
  - TX and RX low-density parity check (LDPC) support for improved range and power efficiency.
  - Dual-stream spatial multiplexing up to 1200 Mbps data rate.
  - 20, 40, 80 MHz channels with optional SGI. (1024 QAM modulation)
  - IEEE 802.11ax beam forming.
  - Client MU-MIMO.
  - Supports 2 antennas with two for shared BT and WLAN port.
    - Supports PCI express revision 3.0 and power management running at Gen2 speeds.
  
  - BT host digital interface:
    - HCI UART (up to 4 Mbps)
    - PCM for audio data
  - Complies with Bluetooth Core Specification Version 5.0 with provisions for supporting future specifications. With Bluetooth Class 1 or Class2 transmitter operation.
  - Supports extended synchronous connections (eSCO), for enhanced voice quality by allowing for retransmission of dropped packets.
  - Adaptive frequency hopping (AFH) for reducing radio frequency interference.
- A simplified block diagram of the module is depicted in the figure above.



## 2. General Specification

### 2.1 General Specification

Model Name	AP6275P
Product Description	2T2R 802.11 ax/ac/a/b/g/n Wi-Fi + BT 5.0 Module
Dimension	L x W: 15 x 13(typical) mm H: 1.55(Maximum) mm
WiFi Interface	Support PCIe v3.0 compliant and runs at Gen2 speeds.
BT Interface	UART / PCM
Operating temperature	-30°C to 85°C
Storage temperature	-40°C to 105°C
Humidity	Operating Humidity 10% to 95% Non-Condensing

Note: The optimal RF performance specified in the data sheet, however, is guaranteed only -10 °C to +55 °C and  $3.2V < V_{BAT} < 3.6V$  without derating performance.

### 2.2 DC Characteristics

#### 2.2.1 Absolute Maximum Ratings

Symbol	Description	Min.	Max.	Unit
V <sub>BAT</sub>	Input supply Voltage	-0.5	4.5	V
V <sub>DDIO</sub>	Digital/ Bluetooth/ I/O Voltage	-0.5	2.07	V

Extreme caution must be exercised to prevent electrostatic discharge (ESD) damage.

Symbol	Condition	ESD Rating	Unit
ESD_HAND_HBM	Human body model contact discharge per JEDEC EID/JESD22-A114	1.5	kV
ESD_HAND_CDM	Charged device model contact discharge per JEDEC EIA/JESD22-C101	300	V



## 2.2.2 Recommended Operating Rating

The module requires two power supplies: VBAT and VDDIO.

Voltage rails	Min.	Typ.	Max.	Unit
VBAT	3.0	3.3	3.8	V
VDDIO	1.68	1.8	1.98	V

VBAT current consumption 1200mA(Peak), when VBAT = 3.3V

The module requires two power supplies: other Digital I/O Pins.

For VDDIO=1.8V	Min.	Max.	Unit
VIL/VIH	0.4×VDDIO	0.65×VDDIO	V
VOL/VOH output@2mA	0.4	VDDIO-0.4	V



## 3. Wi-Fi RF Specification

### 3.1 2.4GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature	Description				
WLAN Standard	IEEE 802.11b/g/n & Wi-Fi compliant				
Frequency Range	2.400 GHz ~ 2.4835 GHz (2.4GHz ISM Band)				
Number of Channels	2.4GHz : Ch1 ~ Ch13				
Modulation	802.11b : DQPSK 、 DBPSK 、 CCK 802.11 g/n : OFDM /64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11ax : OFDMA /1024-QAM 、 256-QAM 、 64-QAM 、 16-QAM 、 QPSK 、 BPSK				
<b>Output Power , tolerance <math>\pm 1.5</math> dB</b>					
<b>The transmit EVM quality &amp; spectrum mask are compliant with IEEE 802.11 standard</b>					
802.11b	1Mbps	2Mbps	5.5Mbps	11Mbps	
	19.5	19.5	19.5	19.5	
802.11g	6 、 9Mbps	12 、 18Mbps	24Mbps	36Mbps	48Mbps
	19.5	19.5	18.5	18.5	18
	54Mbps				
802.11n 20MHz	MCS0~2	MCS3	MCS4	MCS5	MCS6
	19.5	18.5	18.5	18	18
	MCS7				
802.11ax 20MHz	HE0~2	HE3	HE4	HE5	HE6
	19.5	18.5	18.5	18	18
	HE7	HE8	HE9	HE10	HE11
	17.5	16.5	16.5	15	15
Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.					
<b>Sensitivity, tolerance <math>\pm 2</math> dB</b>					
<b>CCK modulation PER <math>\leq 8\%</math> 、 OFDM modulation PER <math>\leq 10\%</math></b>					
802.11b	Data Rate	Spec.(dBm)			
	1Mbps	-98			
	2Mbps	-93			
	5.5Mbps	-91			
	11Mbps	-89			



802.11g SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-93	24Mbps	-85
	9Mbps	-92	36Mbps	-82
	12Mbps	-91	48Mbps	-78
	18Mbps	-88	54Mbps	-76
802.11g MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	6Mbps	-95	24Mbps	-87
	9Mbps	-94	36Mbps	-84
	12Mbps	-93	48Mbps	-81
	18Mbps	-90	54Mbps	-78
802.11n_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-93	MCS4	-81.5
	MCS1	-89	MCS5	-79
	MCS2	-87	MCS6	-76
	MCS3	-84	MCS7	-76
802.11n_20MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-93	MCS5	-80
	MCS1	-92	MCS6	-78
	MCS2	-90	MCS7	-76
	MCS3	-87	MCS8	-72
	MCS4	-83	MCS15	-73
802.11ax_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-93	HE6	-76
	HE1	-89	HE7	-76
	HE2	-87	HE8	-72
	HE3	-84	HE9	-70
	HE4	-81.5	HE10	-65
	HE5	-79	HE11	-61.5
Maximum Input Level	802.11b : -10 dBm			
	802.11g/n/ax : -20 dBm			



## 3.2 5GHz RF Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

Feature	Description				
WLAN Standard	IEEE 802.11a/n/ac/ax & Wi-Fi compliant				
Frequency Range	5.15~5.35GHz 、 5.47~5.725GHz 、 5.725~5.85GHz (5GHz UNII Band)				
Number of Channels	5.15~5.35GHz : Ch36 ~ Ch64 5.47~5.725GHz : Ch100 ~ Ch140 5.725~5.85GHz : Ch149 ~ Ch165				
Modulation	802.11a : OFDM /64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11n : OFDM /64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11ac : OFDM /256-QAM 、 OFDM /64-QAM 、 16-QAM 、 QPSK 、 BPSK 802.11ax : OFDMA/ 1024-QAM 、 OFDM /256-QAM 、 OFDM /64-QAM 、 16-QAM 、 QPSK 、 BPSK				
<b>Output Power , tolerance <math>\pm</math> 2 dB</b>					
<b>The transmit EVM quality &amp; spectrum mask are compliant with IEEE 802.11 standard</b>					
802.11a	Frequency (MHz)	6~9Mbps	12~18Mbps	24Mbps	36Mbps
	5150~5350	16.5	16.5	16	16
	5470~5720	16.5	16.5	16	16
	5725~5845	16.5	16.5	16	16
	Frequency (MHz)	48Mbps	54Mbps		
	5150~5350	15.5	15.5		
	5470~5720	15.5	15.5		
	5725~5845	15.5	15.5		
802.11n 20MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	16	15.5	15.5
	5470~5720	16	16	15.5	15.5
	5725~5845	16	16	15.5	15.5
	Frequency (MHz)	MCS6	MCS7		
	5150~5350	14.5	14.5		
	5470~5720	14.5	14.5		
	5725~5845	14.5	14.5		



802.11n 40MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	16	15	15
	5470~5720	16	16	15	15
	5725~5845	16	16	15	15
	Frequency (MHz)	MCS6	MCS7		
	5150~5350	14.5	14.5		
	5470~5720	14.5	14.5		
	5725~5845	14.5	14.5		
802.11ac 20MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	16	15.5	15.5
	5470~5720	16	16	15.5	15.5
	5725~5845	16	16	15.5	15.5
	Frequency (MHz)	MCS6	MCS7	MCS8	
	5150~5350	14.5	14.5	12	
	5470~5720	14.5	14.5	12	
	5725~5845	14.5	14.5	12	
802.11ac 40MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	15	15	15
	5470~5720	16	15	15	15
	5725~5845	16	15	15	15
	Frequency (MHz)	MCS6	MCS7	MCS8	MCS9
	5150~5350	14.5	14.5	12	10
	5470~5720	14.5	14.5	12	10
	5725~5845	14.5	14.5	12	10
802.11ac 80MHz	Frequency (MHz)	MCS0~2	MCS3	MCS4	MCS5
	5150~5350	16	15	14	14
	5470~5720	16	15	14	14
	5725~5845	16	15	14	14
	Frequency (MHz)	MCS6	MCS7	MCS8	MCS9
	5150~5350	14.5	14.5	10	10
	5470~5720	14.5	14.5	10	10
	5725~5845	14.5	14.5	10	10



802.11ax 20MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	16.5	15.5	15.5	15.5
	5470~5720	16.5	15.5	15.5	15.5
	5725~5845	16.5	15.5	15.5	15.5
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	14.5	12	12
	5470~5720	14.5	14.5	12	12
	5725~5845	14.5	14.5	12	12
	Frequency (MHz)	HE10	HE11		
	5150~5350	10	10		
	5470~5720	10	10		
	5725~5845	10	10		
802.11ax 40MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	16	15	15	15
	5470~5720	16	15	15	15
	5725~5845	16	15	15	15
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	14.5	12	10
	5470~5720	14.5	14.5	12	10
	5725~5845	14.5	14.5	12	10
	Frequency (MHz)	HE10	HE11		
	5150~5350	8	8		
	5470~5720	8	8		
	5725~5845	8	8		
802.11ax 80MHz	Frequency (MHz)	HE0~2	HE3	HE4	HE5
	5150~5350	16	15	15	15
	5470~5720	16	15	15	15
	5725~5845	16	15	15	15
	Frequency (MHz)	HE6	HE7	HE8	HE9
	5150~5350	14.5	14.5	10	10
	5470~5720	14.5	14.5	10	10
	5725~5845	14.5	14.5	10	10
	Frequency (MHz)	HE10	HE11		
	5150~5350	9	9		
	5470~5720	9	9		
	5725~5845	9	9		

Note: The specifications of RF output power are subject to change to fulfill the safety regulation and requirements in end-user product.



**Sensitivity, tolerance  $\pm 2$  dB**  
**OFDM modulation PER  $\leq 10\%$**

	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
802.11a SISO	6Mbps	-90.5	24Mbps	-83
	9Mbps	-90	36Mbps	-80
	12Mbps	-88	48Mbps	-75
	18Mbps	-86	54Mbps	-73
MIMO802.11a MIMO	6Mbps	-92	24Mbps	-86
	9Mbps	-91	36Mbps	-83
	12Mbps	-90	48Mbps	-78
	18Mbps	-89	54Mbps	-77
802.11n_20MHz SISO	MCS0	-90	MCS4	-79
	MCS1	-88	MCS5	-76
	MCS2	-86	MCS6	-73
	MCS3	-83	MCS7	-72
802.11n_20MHz MIMO	MCS0	-92	MCS5	-78
	MCS1	-91	MCS6	-76
	MCS2	-89	MCS7	-75
	MCS3	-86	MCS8	-89
	MCS4	-82	MCS15	-70
802.11n_40MHz SISO	MCS0	-88	MCS4	-77
	MCS1	-86	MCS5	-72
	MCS2	-83	MCS6	-70
	MCS3	-80	MCS7	-69
802.11n_40MHz MIMO	MCS0	-88	MCS5	-75
	MCS1	-88	MCS6	-73
	MCS2	-86	MCS7	-72
	MCS3	-83	MCS8	-86
	MCS4	-79	MCS15	-67

802.11ac_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-90	MCS5	-75
	MCS1	-88	MCS6	-73
	MCS2	-86	MCS7	-70
	MCS3	-83	MCS8	-68
	MCS4	-79		
802.11ac_20MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-92	MCS6,NSS=1	-76
	MCS1,NSS=1	-91	MCS7,NSS=1	-75
	MCS2,NSS=1	-88	MCS8,NSS=1	-72
	MCS3,NSS=1	-85	MCS0,NSS=2	-88
	MCS4,NSS=1	-82	MCS8,NSS=2	-65
	MCS5,NSS=1	-77		
802.11ac_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-88	MCS5	-72
	MCS1	-86	MCS6	-70
	MCS2	-83	MCS7	-69
	MCS3	-80	MCS8	-65
	MCS4	-76	MCS9	-64
802.11ac_40MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-90	MCS6,NSS=1	-73
	MCS1,NSS=1	-88	MCS7,NSS=1	-72
	MCS2,NSS=1	-86	MCS8,NSS=1	-68
	MCS3,NSS=1	-82	MCS9,NSS=1	-66
	MCS4,NSS=1	-79	MCS0,NSS=2	-86
	MCS5,NSS=1	-77	MCS9,NSS=2	-60
802.11ac_80MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0	-85	MCS5	-68
	MCS1	-82	MCS6	-67
	MCS2	-79	MCS7	-65
	MCS3	-76	MCS8	-62
	MCS4	-73	MCS9	-61



802.11ac_80MHz MIMO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	MCS0,NSS=1	-87	MCS6,NSS=1	-70
	MCS1,NSS=1	-85	MCS7,NSS=1	-68
	MCS2,NSS=1	-82	MCS8,NSS=1	-66
	MCS3,NSS=1	-79	MCS9,NSS=1	-63
	MCS4,NSS=1	-76	MCS0,NSS=2	-83
	MCS5,NSS=1	-71	MCS9,NSS=2	-58
802.11ax_20MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-90	HE6	-73
	HE1	-88	HE7	-70
	HE2	-86	HE8	-68
	HE3	-83	HE9	-64
	HE4	-79	HE10	-59
	HE5	-75	HE11	-57
802.11ax_40MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-90	HE6	-73
	HE1	-88	HE7	-70
	HE2	-86	HE8	-68
	HE3	-83	HE9	-64
	HE4	-79	HE10	-60
	HE5	-75	HE11	-55
802.11ax_80MHz SISO	Data Rate	Spec.(dBm)	Data Rate	Spec.(dBm)
	HE0	-90	HE6	-73
	HE1	-88	HE7	-70
	HE2	-86	HE8	-68
	HE3	-83	HE9	-61
	HE4	-79	HE10	-57
	HE5	-75	HE11	-53
Maximum Input Level	802.11a/n/ac/ax : -30 dBm			



## 4. Bluetooth Specification

### 4.1 Bluetooth Specification

Conditions : VBAT=3.3V ; VDDIO=1.8V ; Temp:25°C

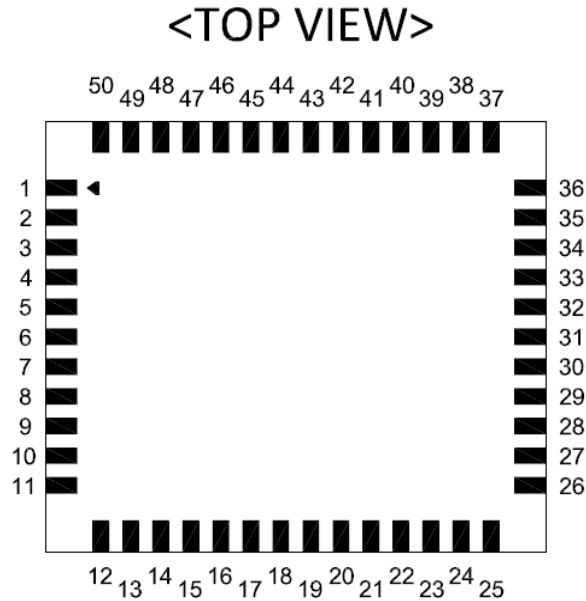
Feature	Description
<b>General Specification</b>	
Bluetooth Standard	GFSK 、 DQPSK 、 8DPSK 、 LE(1Mbps) 、 2LE(2Mbps)
Host Interface	UART
Frequency Band	2402 MHz ~ 2480 MHz
Number of Channels	79 channels for classic 、 40 channels for BLE
Modulation	FHSS, GFSK, DPSK, DQPSK
<b>RF Specification</b>	
<b>Output Power , tolerance ± 1.5 dB</b>	
	<b>CL1 (dBm)</b>
BDR Output Power	8
EDR Output Power	6
BLE Output Power	7
<b>Sensitivity, tolerance ± 1.5 dB</b>	
Sensitivity @ BER=0.1% for GFSK (1Mbps)	-88 dBm
Sensitivity @ BER=0.01% for $\pi/4$ -DQPSK (2Mbps)	-91 dBm
Sensitivity @ BER=0.01% for 8DPSK (3Mbps)	-85 dBm
Sensitivity @ BER=0.01% for LE (1Mbps)	-90 dBm
Sensitivity @ BER=0.01% for 2LE (2Mbps)	-91 dBm
Maximum Input Level	GFSK (1Mbps):-20dBm
	$\pi/4$ -DQPSK (2Mbps) :-20dBm
	8DPSK (3Mbps) :-20dBm

Note\* : The Bluetooth BDR output power is able to be configured by firmware (hcd file).



## 5. Pin Definition

### 5.1 Pin Outline



### 5.2 Pin Assignment

NO	Name	Type	Description
1	GND	—	Ground connections
2	WL_ANT0	I/O	RF I/O port0
3	GND	—	Ground connections
4	GND	—	Ground connections
5	GND	—	Ground connections
6	GND	—	Ground connections
7	GND	—	Ground connections
8	GND	—	Ground connections
9	WL_ANT1	I/O	RF I/O port1
10	GND	—	Ground connections
11	GND	—	Ground connections
12	PCIE_PREST_L	I	PCIe host indication to reset the device
13	XTAL_XOP	I	Xtal oscillator input
14	XTAL_XON	O	Xtal oscillator output
15	WL_REG_ON	I	Low asserting reset for WiFi core

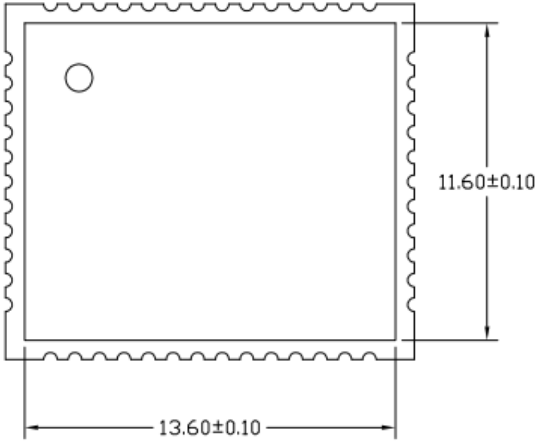


16	WL_HOST_WAKE	O	WLAN to wake-up HOST
17	NC	—	Floating (Don't connected to ground)
18	NC	—	Floating (Don't connected to ground)
19	BT_PCM_OUT	O	PCM Data output
20	BT_PCM_IN	I	PCM data input
21	BT_PCM_SYNC	I/O	PCM sync signal
22	BT_PCM_CLK	I	PCM clock
23	GND	—	Ground connections
24	PCIE_PME_L	OD	PCI power management event output
25	CBUCK_OP9	I	Internal Buck voltage generation pin
26	CSR_VLX	O	Internal Buck voltage generation pin
27	GND	—	Ground connections
28	ASR_VLX	O	Internal Analog Buck voltage generation pin
29	ABUCK_1P12	I	Internal Analog Buck voltage generation pin
30	GND	—	Ground connections
31	LPO_IN	I	External Low Power Clock input (32.768KHz)
32	GND	—	Ground connections
33	PCIE_RCLK_N	I	PCI Express differential clock input-Negative
34	VDDIO	P	I/O Voltage supply input
35	PCIE_RCLK_P	I	PCI Express differential clock input-Positive
36	VBAT	P	Main power voltage source input
37	PCIE_CLKREQ_L	OD	PCIe clock request
38	BT_REG_ON	I	Low asserting reset for Bluetooth core
39	GND	—	Ground connections
40	BT_UART_TXD	O	Bluetooth UART serial data output
41	BT_UART_RXD	I	Bluetooth UART serial data input
42	BT_UART_RTS_N	O	Bluetooth UART request to send
43	BT_UART_CTS_N	I	Bluetooth UART clear to send
44	PCIE_RX_N	I	PCI Express receive data-Negative
45	PCIE_RX_P	I	PCI Express receive data-Positive
46	PCIE_TX_N	O	PCI Express transmit data-Negative
47	PCIE_TX_P	O	PCI Express transmit data-Positive
48	NC	—	Floating (Don't connected to ground)
49	BT_WAKE	I	HOST wake-up Bluetooth device
50	BT_HOST_WAKE	O	Bluetooth device to wake-up HOST

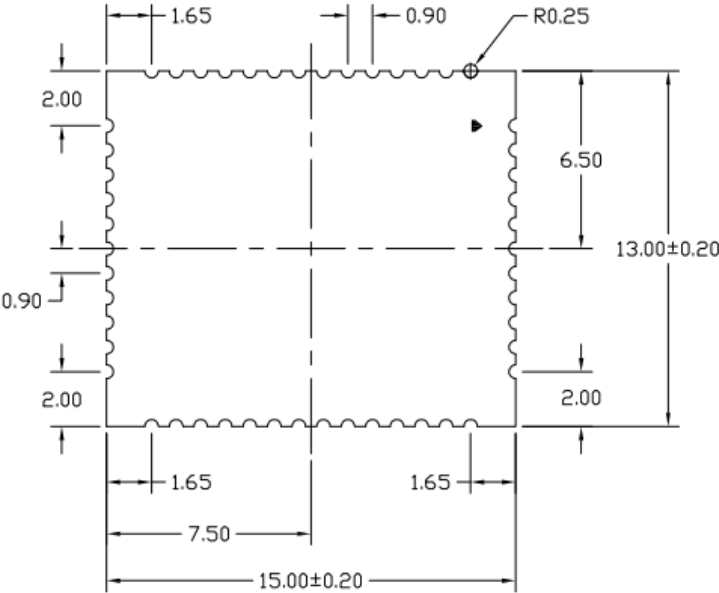
# 6. Dimensions

## 6.1 Module Dimensions

<TOP VIEW>



<BOTTOM VIEW>



<SIDE VIEW>



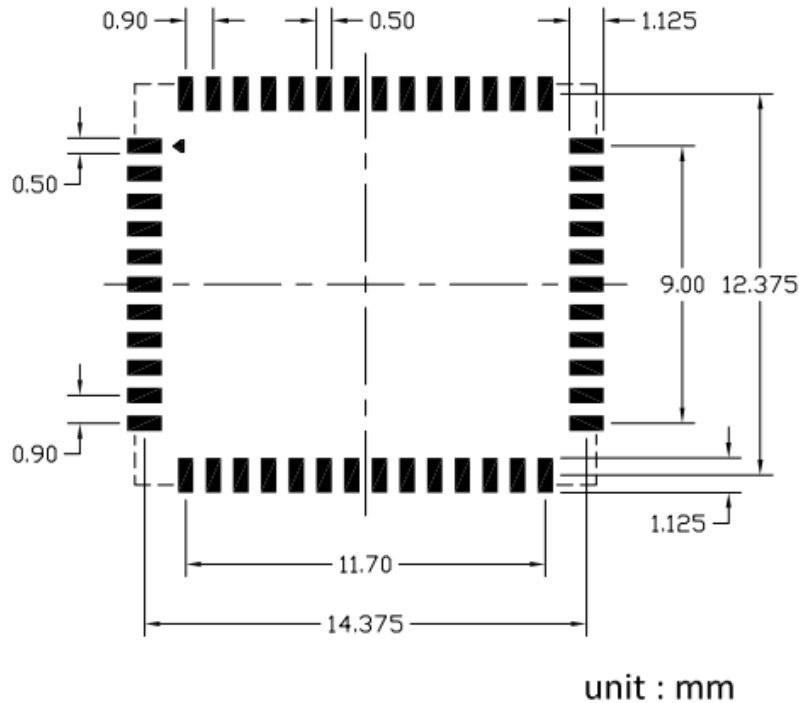
unit : mm

Note, X = 1.55mm

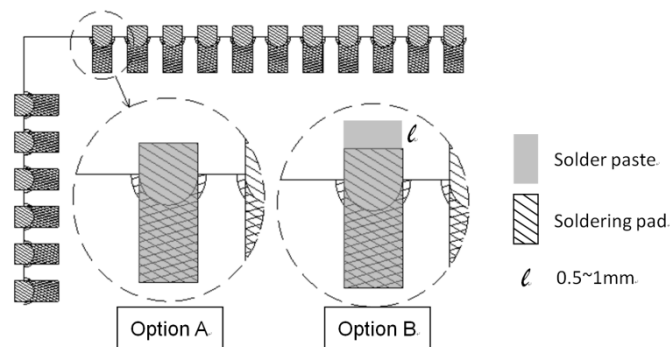


## 6.2 Recommended footprint

<TOP VIEW>



- Solder paste layer design is generally the same as recommended footprint.  
(錫膏層設計通常建議和焊墊尺寸相同)
- If soldering quality with good wetting on upright side is essential for PQC, how to optimize the aperture design in the stencil to adjust the amount of solder paste would be crucial.  
In addition, a kind of stencil design with stepped thickness in partial area would be considered if the thickness of stencil is about 0.1mm or thinner. Please optimize the stencil design by manufacture engineer or contact AMPAK FAE for assistance.  
(如果模組吃錫品質考量側面爬錫，如何優化鋼網開孔設計以調整適當的錫膏量是非常重要的。尤其鋼網的厚度大約是 0.1mm 或更薄時，可考慮局部加厚鋼網的設計。請諮詢製程工程師以優化鋼網的設計,或是聯絡正基科技技術支持團隊).



## 7. External clock reference

### External LPO signal characteristics

Parameter	Specification	Units
Nominal input frequency	32.768	kHz
Frequency accuracy	+/-25	ppm
Duty cycle	30 - 70	%
Input signal amplitude	1.8±0.09	V
Signal type	Square-wave or sine-wave	-
Input impedance	>100k <5	Ω pF
Clock jitter (integrated over 300Hz – 15KHz)	<1	Hz
Output high voltage	0.7V <sub>io</sub> - V <sub>io</sub>	V

### External 37.4MHz X'TAL characteristics

Parameter	Specification	Units
Nominal frequency - F <sub>0</sub>	37.4	MHz
Frequency Tolerance - $\Delta F / F_0$ (At 25°C +/- 3°C)	+/- 5	ppm
Operation Temperature Range - Topr	-40 ~ + 85	°C
Freq. Stability(over operating temperature) - TC Ref. to 25°C	+/- 15	ppm
Load capacitance - CL	16	pF
Equivalent Series Resistance – ESR	Max. 60	Ω
Drive Level - DL	Typ. 50, Max. 100	μW
Insulation resistance – IR At 100Vdc	Min. 500	MΩ

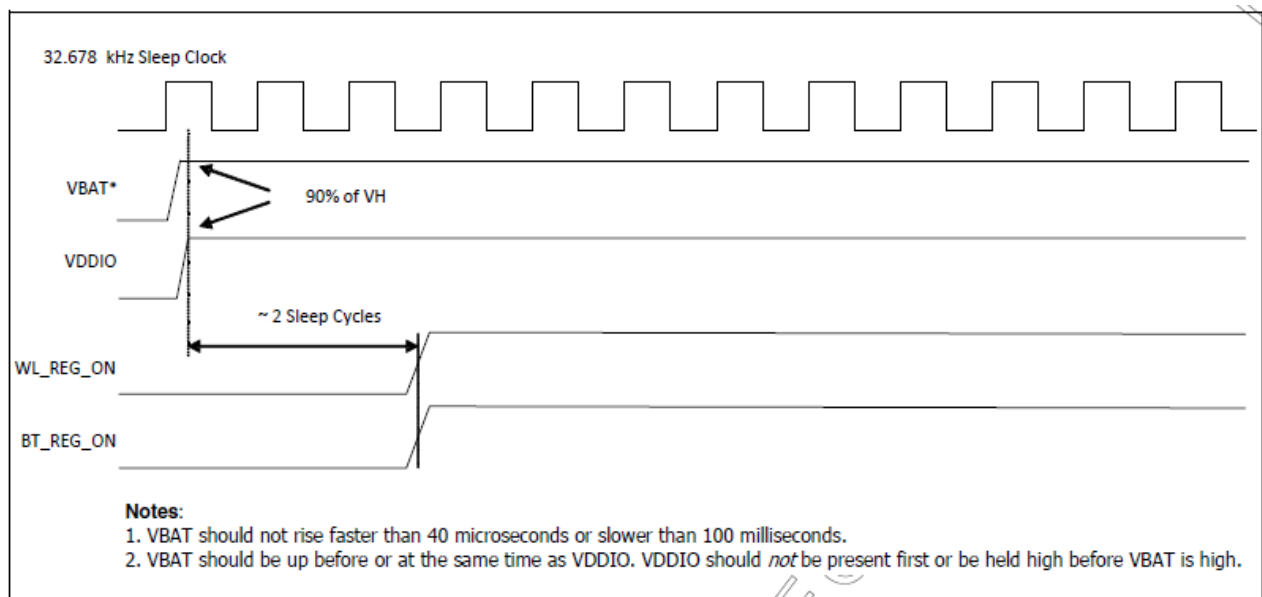
## 8. Host Interface Timing Diagram

### 8.1 Power-up Sequence Timing Diagram

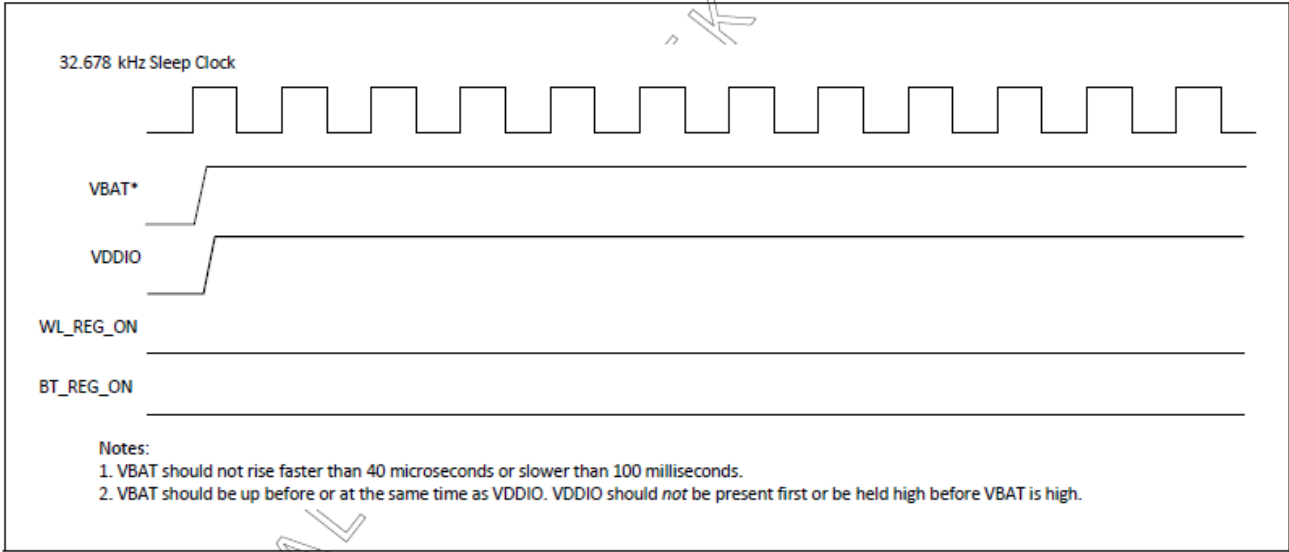
The module has signals that allow the host to control power consumption by enabling or disabling the Bluetooth, WLAN and internal regulator blocks. These signals are described below.

Additionally, diagrams are provided to indicate proper sequencing of the signals for various operating states. The timing value indicated are minimum required values: longer delays are also acceptable.

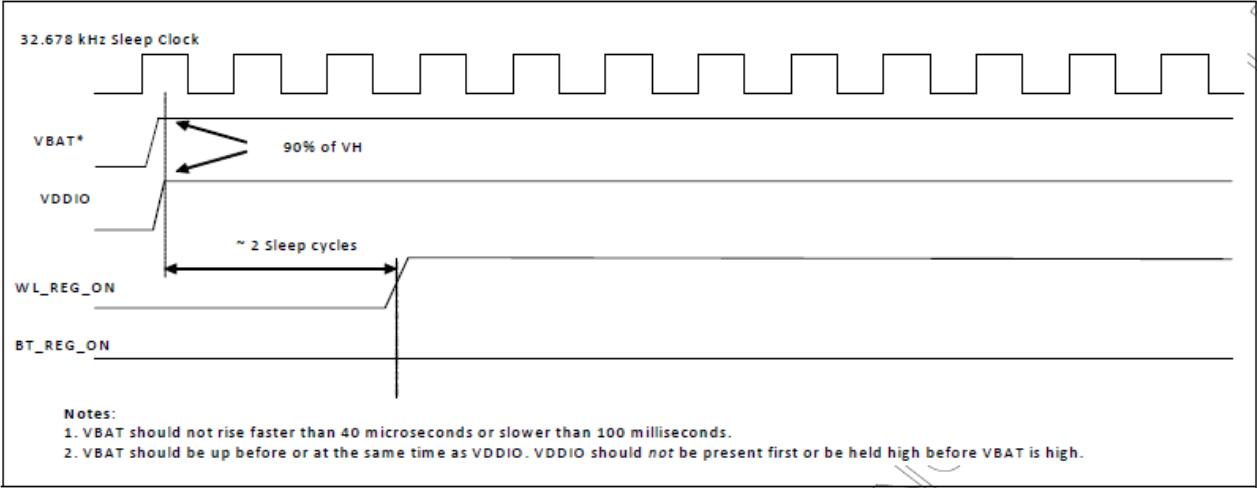
- **WL\_REG\_ON:** Used by the PMU to power up or power down the internal regulators used by the WLAN section. When this pin is high, the regulators are enabled and the WLAN section is out of reset. When this pin is low the WLAN section is in reset.
- **BT\_REG\_ON:** Used by the PMU to power up or power down the internal regulators used by the BT section. Low asserting reset for Bluetooth. This pin has no effect on WLAN and does not control any PMU functions. This pin must be driven high or low (not left floating).



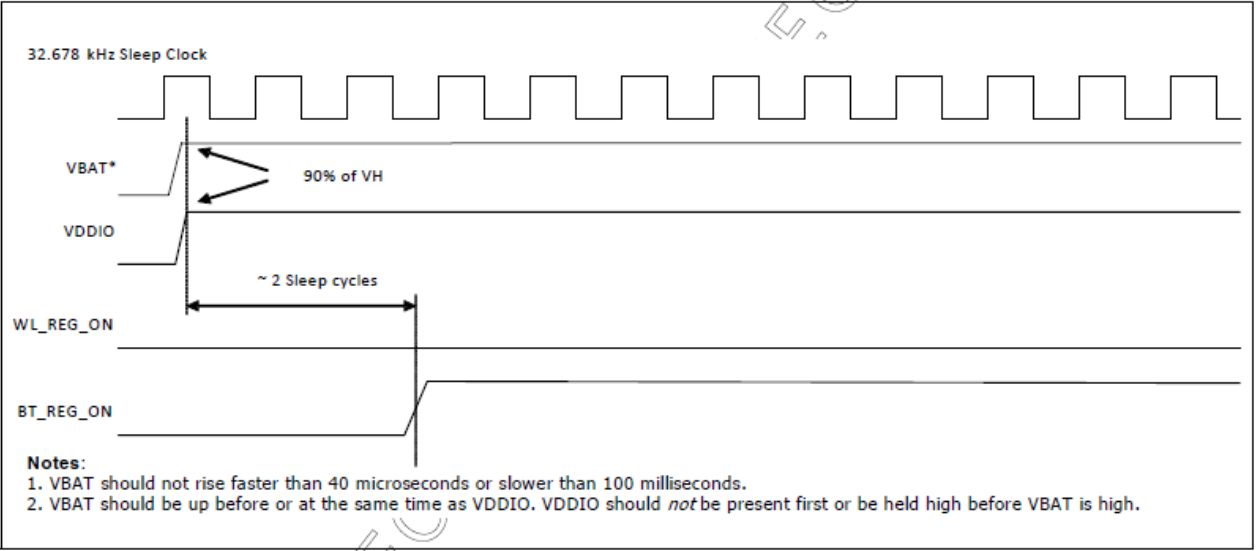
WLAN=ON, Bluetooth=ON



WLAN=OFF, Bluetooth=OFF



WLAN=ON, Bluetooth=OFF



WLAN=OFF, Bluetooth=ON





## 8.2 PCIe Interface Description

The PCI Express(Pcie) core on the AP6275P is a high-performance serial I/O interconnect that is protocol compliant and electrically compatible with the PCI Express Base Specification v3.0 running at Gen2 speeds.

PCI Express Interface Parameters

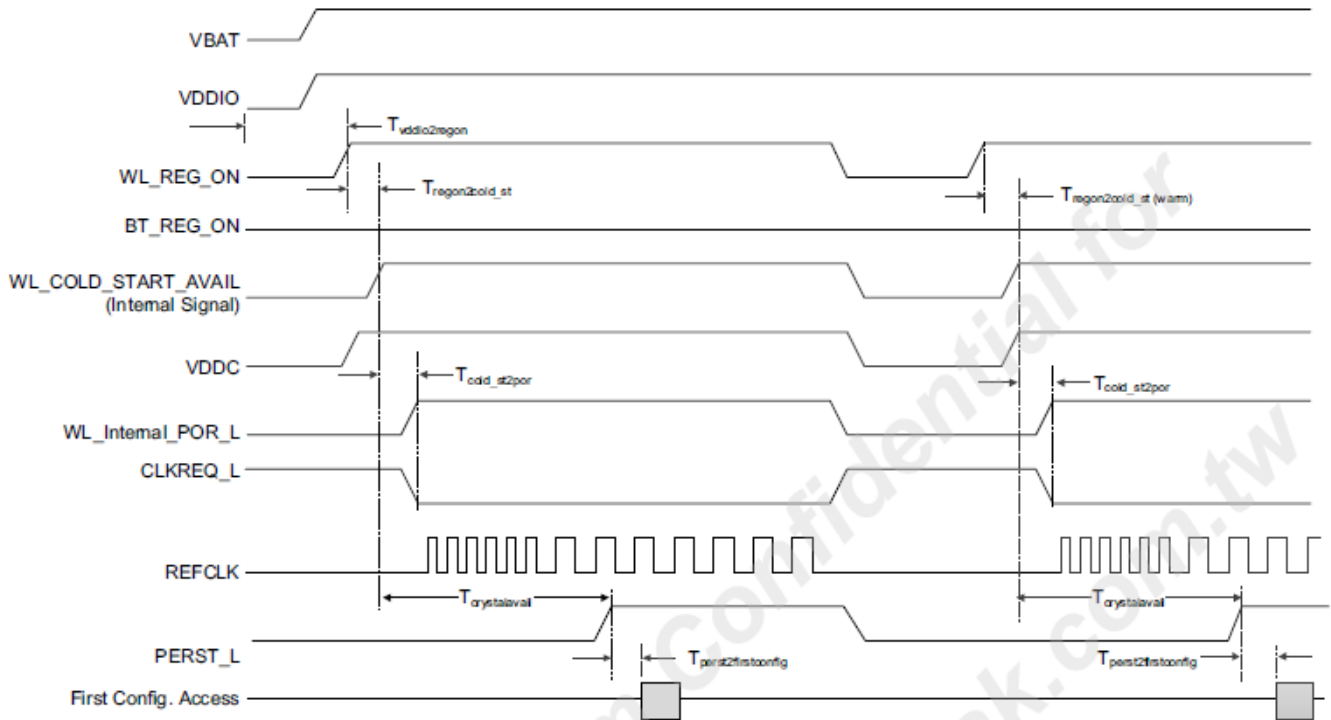
Parameter	Symbol	Comments	Min.	Typ.	Max.	Unit
<b>General<sup>a</sup></b>						
Baud rate	BPS	—	—	5	—	Gbaud
Reference clock peak-to-peak differential <sup>b</sup>	Vref	LVPECL, AC coupled	0.95	—	—	V
<b>Receiver</b>						
Differential termination	ZRX-DIFF-DC	Differential termination	80	100	120	Ω
DC impedance	ZRX-DC	DC common-mode impedance	40	50	60	Ω
Powered down termination (POS)	ZRX-HIGH-IMP-DC-POS	Power-down or RESET high impedance	100k	—	—	Ω
Powered down termination (NEG)	ZRX-HIGH-IMP-DC-NEG	Power-down or RESET high impedance	1k	—	—	Ω
Input voltage	VRX-DIFFp-p	AC coupled, differential p-p	175	—	—	mV
Jitter tolerance	TRX-EYE	Minimum receiver eye width	0.4	—	—	UI
Differential return loss	RLRX-DIFF	Differential return loss	10	—	—	dB
Common-mode return loss	RLRX-CM	Common-mode return loss	6	—	—	dB
Unexpected electrical idle enter detect threshold integration time	TRX-IDEL-DET-DIFF-ENTERTIME	An unexpected electrical idle must be recognized no longer than this time to signal an unexpected idle condition.	—	—	10	ms
Signal detect threshold	VRX-IDLE-DET-DIFFp-p	Electrical idle detect threshold	65	—	175	mV
<b>Transmitter</b>						
Output voltage	VTX-DIFFp-p	Differential p-p, programmable in 16 steps	0.8	—	1200	mV
Output voltage rise time	VTX-RISE	20% to 80%	0.125 (2.5 GT/s) 0.15 (5 GT/s)	—	—	UI
Output voltage fall time	VTX-FALL	80% to 20%	0.125 (2.5 GT/s) 0.15 (5 GT/s)	—	—	UI
RX detection voltage swing	VTX-RCV-DETECT	The amount of voltage change allowed during receiver detection.	—	—	600	mV



## PCI Express Interface Parameters (Continued)

Parameter	Symbol	Comments	Min.	Typ.	Max.	Unit
TX AC peak common-mode voltage (5 GT/s)	VTX-CM-AC-PP	TX AC common mode voltage (5 GT/s)	—	—	100	mV
TX AC peak common-mode voltage (2.5 GT/s)	VTX-CM-AC-P	TX AC common mode voltage (2.5 GT/s)	—	—	20	mV
Absolute delta of DC common-mode voltage during L0 and electrical idle	VTX-CM-DC-ACTIVE-IDLE-DELTA	Absolute delta of DC common-mode voltage during L0 and electrical idle.	0	—	100	mV
Absolute delta of DC common-mode voltage between D+ and D-	VTX-CM-DC-LINE-DELTA	DC offset between D+ and D-	0	—	25	mV
Electrical idle differential peak output voltage	VTX-IDLE-DIFF-AC-p	Peak-to-peak voltage	0	—	20	mV
TX short circuit current	ITX-SHORT	Current limit when TX output is shorted to ground.	—	—	90	mA
DC differential TX termination	ZTX-DIFF-DC	Low impedance defined during signaling (parameter is captured for 5.0 GHz by RLTX-DIFF)	80	—	120	$\Omega$
Differential return loss	RLTX-DIFF	Differential return loss	10 (min) for 0.05: 1.25 GHz	—	—	dB
Common-mode return loss	RLTX-CM	Common-mode return loss	6	—	—	dB
TX eye width	TTX-EYE	Minimum TX eye width	0.75	—	—	UI

## PCIe Power-On Timing



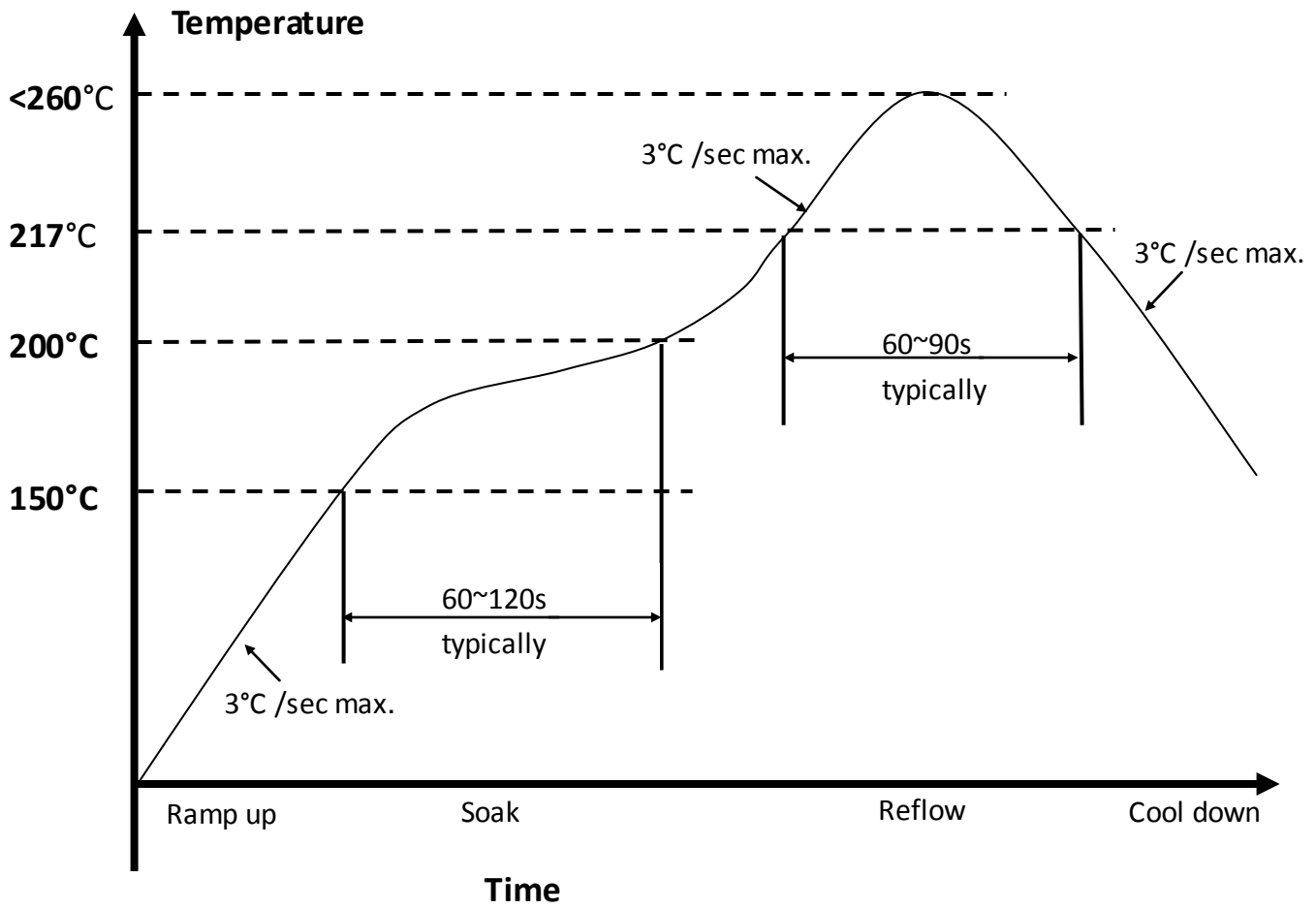
Timing Parameter	Notes	Value <sup>a</sup>	Unit
$T_{vddio2regon}$	–	0.1	ms
$T_{regon2cold\_st}$	3.4 ms + 162 instruction-level parallelism (ILP) cycles	10.13	ms
$T_{cold\_st2por}$	54 ILP cycles	2.24	ms
$T_{crystalavail}$	509 ILP cycles	21.17	ms
$T_{perst2firstconfig}$	–	6.0	ms
$T_{vddioon2firstconfig}$	$T_{vddio2regon} + T_{regon2cold\_st} + T_{crystalavail} + T_{perst2firstconfig}$	37.4 <sup>b</sup>	ms
$T_{regon2cold\_st (warm)}$	162 ILP cycles	6.73	ms

a. The time values assume an ILP tolerance of  $\pm 30\%$ .

b. With VDDIO as a reference, 37.4 ms is the minimum system wait time before issuing the first configuration access.

## 9. Recommended Reflow Profile





1. Referred to IPC/JEDEC standard
2. Peak Temperature :  $<260^{\circ}\text{C}</math>$
3. Cycle of Reflow : 2 times max.
4. Adding Nitrogen ( $\text{N}_2$ ) to implement 2000ppm or less of oxygen concentration during reflow process is recommended.
5. If the shelf time is exceeded, be sure baking step to remove the moisture from the component

## 10. Package Information

AMPAK Technology Inc.

3F., No.15-1, Zhonghua Rd., Hukou Township, Hsinchu County, Taiwan, 30352

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<http://www.ampak.com.tw>




## 10.1 Label

Label A → Anti-static and humidity notice



Label B → MSL caution / Storage Condition

	<b>Caution</b> This bag contains <b>MOISTURE-SENSITIVE DEVICES</b>	LEVEL <input type="text"/>
	<small>If blank, see adjacent bar code label</small>	
<ol style="list-style-type: none"> <li>Calculated shelf life in sealed bag: 12 months at &lt;40°C and &lt;90% relative humidity (RH)</li> <li>Peak package body temperature: _____ °C <small>If blank, see adjacent bar code label</small></li> <li>After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be                         <ol style="list-style-type: none"> <li>Mounted within: _____ hours of factory conditions <small>If blank, see adjacent bar code label</small></li> <li>Stored per J-STD-033</li> </ol> </li> <li>Devices require bake, before mounting, if:                         <ol style="list-style-type: none"> <li>Humidity Indicator Card reads &gt;10% for level 2a - 5a devices or &gt;60% for level 2 devices when read at 23 ± 5°C</li> <li>3a or 3b are not met</li> </ol> </li> <li>If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure</li> </ol>		
Bag Seal Date: _____ <small>If blank, see adjacent bar code label</small>		
<small>Note: Level and body temperature defined by IPC/JEDEC J-STD-020</small>		

Label C → Inner box label .

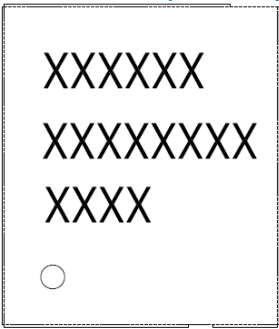
PO:	_____
AMK DEVICE:	_____
PKG S/N:	9PKGYMMDDNNNNN
Model Name:	APXXXXXXXX (R3HF)
P/N:	99X-XXX-XXXXR
Quantity:	1000
Date Code:	YYWW
Lot Code:	XXXXXXXX
	Made in XXXXXX

Label D → Carton box label .

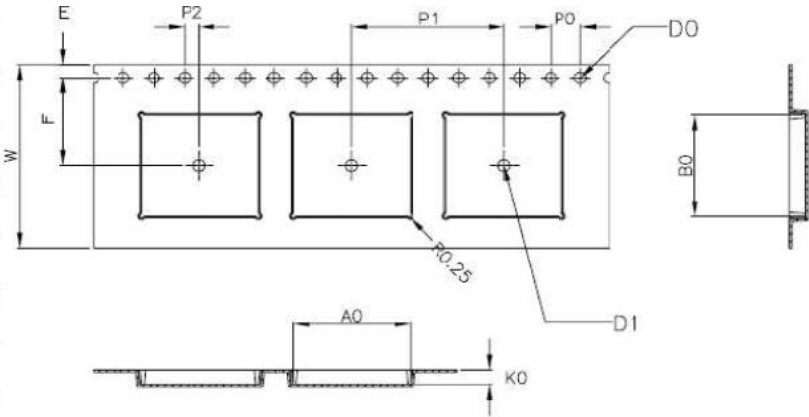
<b>AMPAK Technology Inc.</b>	
PO:	_____
AMK DEVICE:	_____
Model Name:	APXXXXXXXX (R3HF)
Part No.:	99X-XXX-XXXXR
Quantity:	5000
Lot D/C:	XXXXXXXX YYWW 5000
Manufacture:	YYYY/MM/DD
	Made in XXXXXX

## 10.2 Dimension



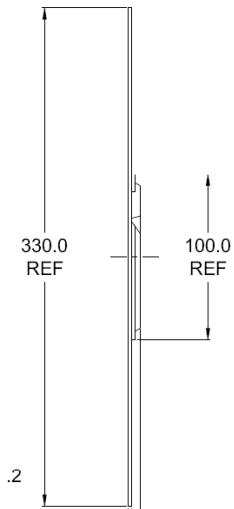
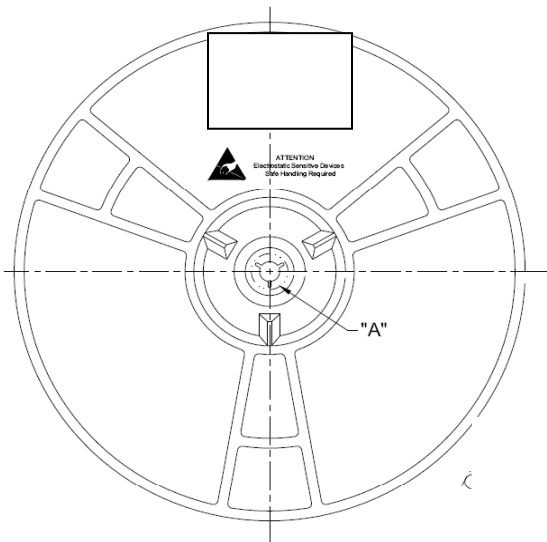


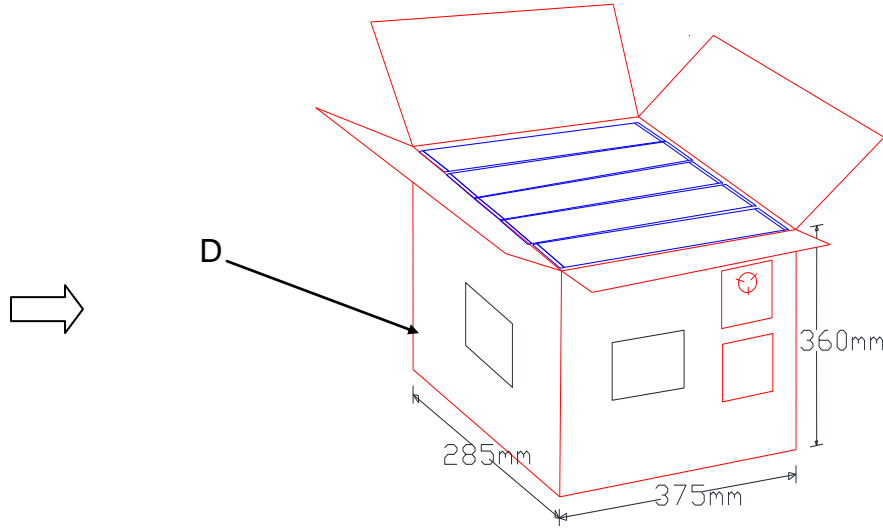
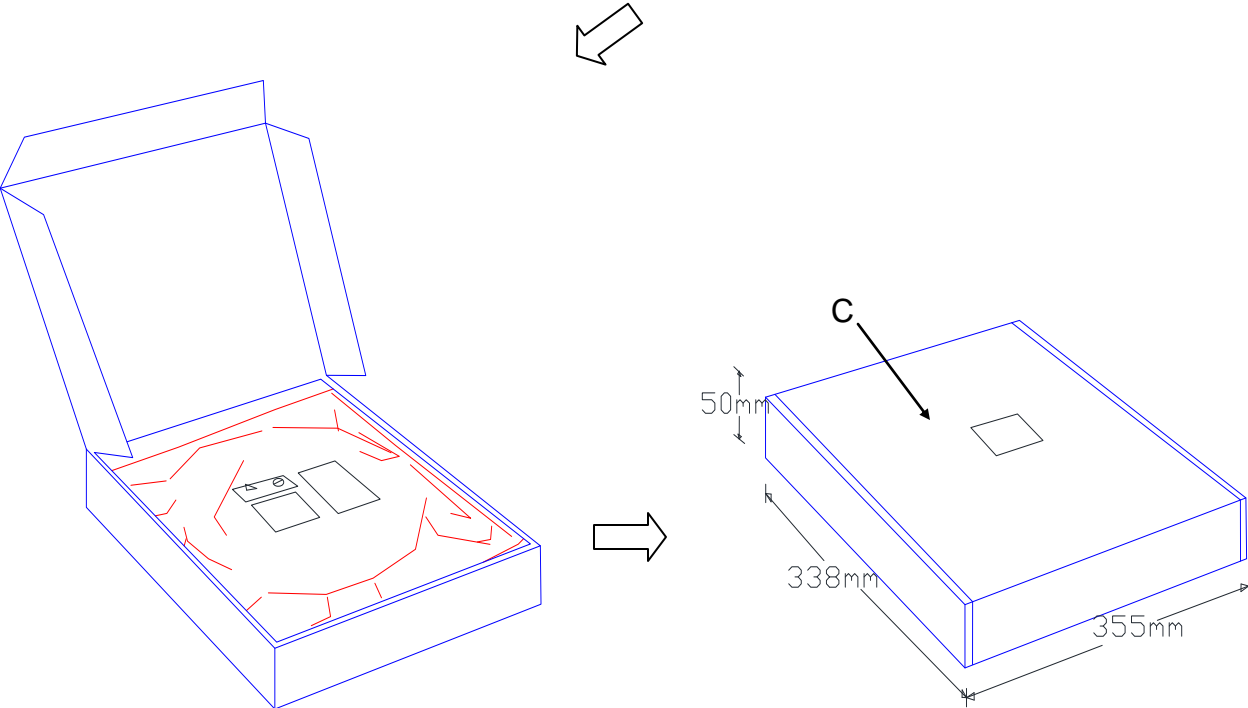
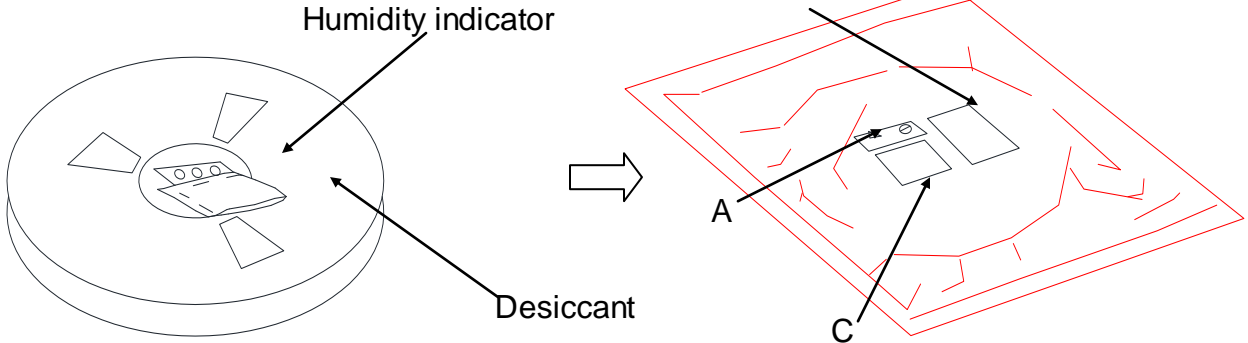
— Part Number  
 — Lot Code  
 — Date Code



W	24.00±0.30
A0	15.30±0.10
B0	13.30±0.10
K0	2.00±0.10
E	1.75±0.10
F	11.50±0.10
P0	4.00±0.10
P1	20.00±0.10
P2	2.00±0.10
D0	1.50 <sup>+0.10</sup> / <sub>-0.00</sub>
D1	∅1.50MIN

1. 10 sprocket hole pitch cumulative tolerance ±0.20.
2. Carrier camber is within 1 mm in 250 mm.
3. Material : Black Conductive Polystyrene Alloy.
4. All dimensions meet EIA-481-D requirements.
5. Thickness: 0.30±0.05mm.
6. Component load per 13" reel : 1000 pcs





### 10.3 MSL Level / Storage Condition





**Caution**  
This bag contains  
**MOISTURE-SENSITIVE DEVICES**

LEVEL

4

If blank, see adjacent  
bar code label

1. Calculated shelf life in sealed bag: 12 months at  $<40^{\circ}\text{C}$  and  $<90\%$  relative humidity (RH)
2. Peak package body temperature: 250  $^{\circ}\text{C}$   
If blank, see adjacent bar code label
3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be
  - a) Mounted within: 72 hours of factory conditions  
If blank, see adjacent bar code label  
 $\leq 30^{\circ}\text{C}/60\%$  RH, or
  - b) Stored per J-STD-033
4. Devices require bake, before mounting, if:
  - a) Humidity Indicator Card reads  $>10\%$  for level 2a-5a devices or  $>60\%$  for level 2 devices when read at  $23\pm 5^{\circ}\text{C}$
  - b) 3a or 3b are not met.
5. If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure.

Bag Seal Date: \_\_\_\_\_  
If blank, see adjacent bar code label

Note: Level and body temperature defined by IPC/JEDEC J-STD-020